Novati to Showcase Positive Results of Hybrid Bonding at IEEE International Interconnect Technology Conference

May 16, 2017 07:00 AM Eastern Daylight Time

Austin, TX – Novati Technologies, LLC, a semiconductor development and commercialization company, will present their poster, "Reliability of Hybrid Bond Interconnects," at the 2017 IEEE International Interconnect Technology Conference in Hsinchu, Taiwan on May 16-18. 3D integration dramatically improves device performance, and hybrid bonding is gaining traction as an advantageous technology for building 3D integrated circuits.

This poster demonstrates the positive results of hybrid bonding at the wafer-level in a reliability study conducted in collaboration with ON Semiconductor [and subsequently published in a white paper under the same title]. The study evaluates and characterizes test structures formed with hybrid bonding techniques, specifically oxide-to-oxide bonds and copper-to-copper bonds.

About Novati Technologies

Novati Technologies is the leading innovation partner for accelerating nanotechnology development and commercialization. Novati's proven advanced technology and secure IP infrastructure combined with its Technology Development Process supports companies developing MEMS, microfluidics, novel transistors, photonics and other nanotechnologies for the Semiconductor, Healthcare & Life Sciences and Aerospace & Defense markets. For more information, visit http://www.Novati-Tech.com.

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